



## Press Release

### **UNISEM RECORDED RM887.7 MILLION (APPROX. US\$293.4 MILLION) REVENUE, RM22.2 MILLION (APPROX. US\$7.3 MILLION) IN NET INCOME FOR 9 MONTHS IN 2011**

**Kuala Lumpur, 1 November 2011** – Unisem (M) Berhad today announced results for the third quarter ended 30 September 2011 (**3Q11**).

The Group recorded revenue of RM288.2 million (approx. US\$95.8 million) for 3Q11, 22.3% decline from the same quarter a year ago (3Q10). For the current quarter the Group achieved net profit of RM4.9 million (approx. US\$1.6 million) compared to RM51.9 million (approx. US\$16.3 million) in 3Q10.

For the 9-month of the current financial year ended 30 September 2011 (**9m11**), the Group recorded revenue of RM887.7 million (approx. US\$293.4 million), a 16.2% decline from that achieved for the 9-month period a year ago (**9m10**). For 9m11, the Group recorded a net profit of RM22.2 million (approx. US\$7.3 million) compared to net profit of RM141.3 million (approx. US\$43.4 million) achieved in 9m10.

The decline in revenue and net profit was principally attributable to decline sales volume and a depreciation in the US\$/RM exchange rate, as compared to the rates that prevailed in 3Q10.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 3Q11 came in at about RM46.6 million (approx. US\$15.5 million), EBITDA margin was about 16%. Equipment capacity utilization averaged at about 60% for the group in 3Q11. Group capital expenditure incurred in 3Q11 was about RM46.1 million (approx. US\$15.3 million), principally for purchase of equipment for wafer bumping, packaging & final test activities at Unisem Chengdu and Unisem (M) Berhad.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "We expect demand for the Group's products and services to remain weak for the next quarter due to global economic uncertainty."

#### **About Unisem**

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at [www.unisemgroup.com](http://www.unisemgroup.com).